SWITCHMODE™ Power Rectifier

DPAK Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Low Forward Voltage Drop
- Low Leakage
- Ultra-Fast Recovery Time
- Pb-Free Package is Available

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 gram (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Reverse Voltage	V_{R}	400	V
verage Rectified Forward Current I _{F(AV}		3	Α
Nonrepetitive Peak Surge Current	I _{FSM}	75	Α
Operating Junction and Storage Temperature Range	$T_{J_i}T_{stg}$	-55 to +175	°C

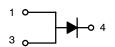
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

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ULTRAFAST RECTIFIER 3 A, 400 V





DPAK CASE 369C

MARKING DIAGRAM



U340 = Specific Device Code A = Assembly Location

Y = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping [†]
MURD340T4	DPAK	2500 / Tape & Reel
MURD340T4G	DPAK (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristics	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{ heta JC}$	2	°C/W
Thermal Resistance – Junction–to–Ambient (Note 1)	$R_{ heta JA}$	49	°C/W

^{1.} Rating applies when surface mounted on a 700 mm², 1 oz Cu heat spreader.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage $ (I_F=3.0~A,~T_J=25^{\circ}C) \\ (I_F=3.0~A,~T_J=150^{\circ}C) $	V _F	1.15 0.92	V
Maximum Instantaneous Reverse Current (Rated V_R) $ (T_J = 25^{\circ}C,400~V) $ $ (T_J = 150^{\circ}C,400~V) $	I _R	5 500	μΑ
Maximum Reverse Recovery Time (I _F = 1.0 A, di/dt = 50 A/ μ s, V _R = 30 V, T _J = 25°C)	t _{rr}	50	ns
ESD Ratings Machine Model = C Human Body Model = 3B		> 400 > 8000	V

TYPICAL CHARACTERISTICS

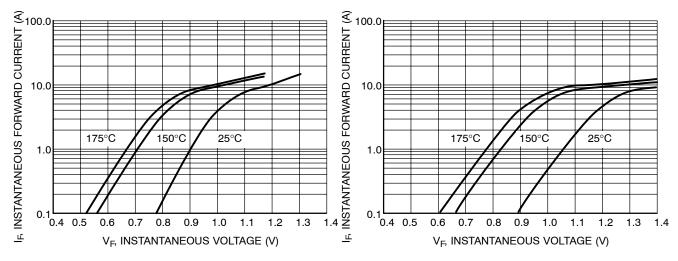


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

TYPICAL CHARACTERISTICS

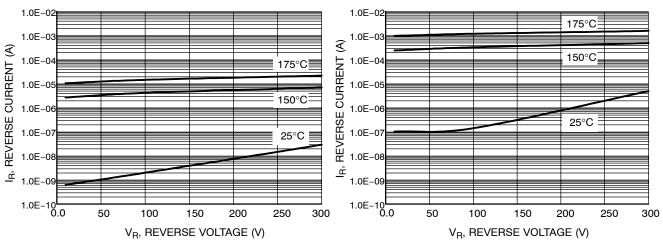
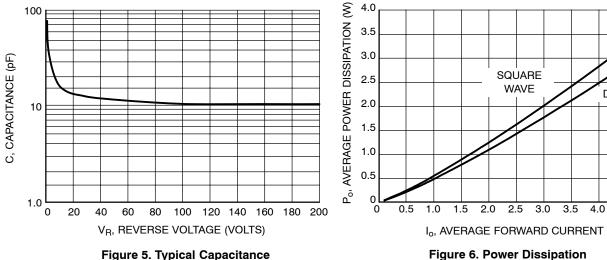


Figure 3. Typical Reverse Voltage

Figure 4. Maximum Reverse Voltage

DC

4.5



DC

SQUARE WAVE

160

150

170

Figure 5. Typical Capacitance

6.0

5.0

4.0

3.0

2.0

1.0

 $R_{\theta JC} = 2^{\circ}C/W$

 $T_J = 175^{\circ}C/W$

110

100

IF, AVERAGE FORWARD CURRENT (A)

6.0 I_F, AVERAGE FORWARD CURRENT (A) $R_{\theta JC} = 2^{\circ}C/W$ 5.0 T_{.1} = 175°C/W 4.0 DC 3.0 SQUARE 2.0 WAVE 1.0 0 180 0 20 80 100 120 160 180 200 TA, AMBIENT TEMPERATURE (°C)

T_C, CASE TEMPERATURE (°C) Figure 7. Current Derating, Case

140

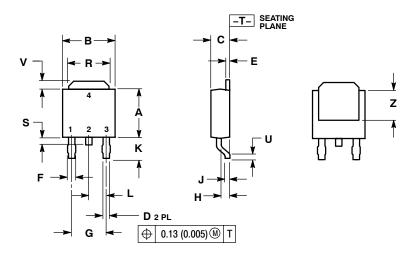
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Figure 8. Current Derating, Ambient

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C-01 ISSUE O

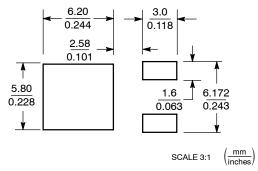


NOTES:

- DIMENSIONING AND TOLERANCING
 PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180 BSC		4.58 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020		0.51	
٧	0.035	0.050	0.89	1.27
Z	0.155		3.93	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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